Display Elektronik GmbH

DATA SHEET

STANDARD OLED/PLED

DEP 096032B-W

Product Specification

Version: 05

06.09.2013

History of Version

Version	Contents	Date	Note
01	NEW VERSION	2009/03/02	SPEC.
02		2009/05/25	PAGE 6
03	Add contrast setting Modify Drawing	2011/12/14	PAGE5 PAGE15
04	UPDATE Quality Assurance · Reliability ADD Precautions for Handling · Precautions for Electrical · Precautions for Storage	2013/08/30	Page 14~21
05	Modify Electrical Characteristics	2013/09/06	Page 6

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1. Numbering System

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2. General Specification

(1) Mechanical Dimension

Item	Standard Value	Unit
Number of dots	96x32	dots
Module dimension (L*W*H)	28.5*11.5*1.41(MAX)	mm
Active area	19.18*6.38	mm
Dot size	0.18(W)×0.18(H)	mm
Dot pitch	0.20(W)×0.20 (H)	mm
Color	White	

(2) Controller IC: SSD1307 Controller

(3) Temperature Range

Operating	-40 ~ +70°C
Storage	-40 ~ +85°C

3. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	ТОР	-40	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	TST	-40	_	+85	$^{\circ}\!\mathbb{C}$
Input Voltage (VDD)	VDD	-0.3	_	4.0	V
Supply Voltage (Vcc)	Vcc	7	_	16	V
Humidity	_	_	_	85	%
Operating lift time	_	_	21000(1)	_	Hrs
Operating lift time	_	_	25000(2)	_	Hrs
Operating lift time	_	_	30000(3)	_	Hrs

Note: (A) Under Vcc = 12V, $Ta = 25^{\circ}C$, 50% RH.

(B) Life time is defined the amount of time when the luminance has decayed to less than 50% of the initial measured luminance.

(C) Note (1) \cdot Note (2) \cdot Note (3) contrast setting are under VDD = 2.8V

(1) Setting of 140 cd/m :

Contrast setting :0x40H Frame rate : 105Hz Duty setting : 1/32

(2) Setting of 120 cd/m :

Contrast setting :0x36H Frame rate : 105Hz Duty setting : 1/32

(3) Setting of 100 cd/m :

Contrast setting :0x2CH Frame rate : 105Hz Duty setting : 1/32

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4. Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	1.65	2.8	3.3	V
Supply Voltage For Panel	Vcc-Vss	_	11.5	12	12.5	V
Input High Vol	V _{IH}	_	$0.8V_{\mathrm{DD}}$	_	_	V
Input Low Vol	V _{IL}	_	_	_	$0.2V_{DD}$	V
Output High Vol	V_{OH}	_	$0.9V_{\mathrm{DD}}$	_	_	V
Output Low Vol.	V_{OL}	_	_	_	$0.1V_{\mathrm{DD}}$	V
Supply Current	I_{DD}	_	_	10	_	mA
Supply Current	I_{CC}	_	_	700	_	uA

5. Optical Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	
View Angle	θ	160	_	-	deg	
Dark Room contrast	CR	2000:1	_	_	_	
Response Time	Т	_	10		us	

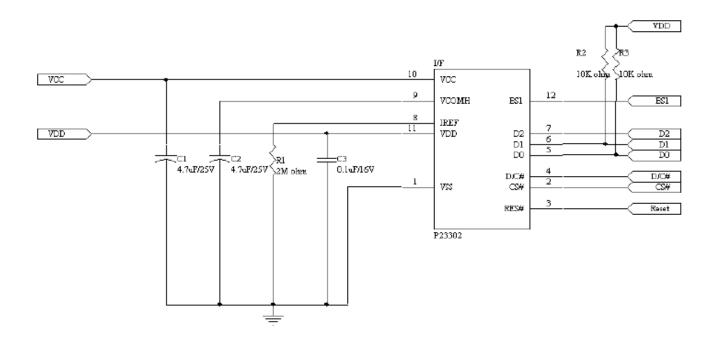
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6. Interface Pin Function

Pin No.	Symbol	Description
1	VSS	This is a ground pin.
2	CS	This pin is the chip select input.
3	RES	Hardware reset signal
4	D/C	In 4-wire Serial mode, this is Data/Command control pin. In I ₂ C mode, this pin acts as SA0 for slave address selection.
5	D0	4-wire SPI: SCLK I ₂ C: SCL
6	D1	4-wire SPI: SDIN I2C: SDAIN
7	D2	4-wire SPI: NC I ₂ C: SDAOUT
8	IREF	The current reference input pin, this pin should be connected to ground through a resistor
9	VCOMH	The COM voltage reference pin, this pin should be connected to ground through a capacitor.
10	VCC	Positive OLED high voltage power supply
11	VDD	Power supply for logic circuit
12	BS1	MCU Bus Interface Pin Selection 0: 4-wire Serial Interface 1: I2C Interface

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7. Power Supply For LCD Module



Component:

C1 · C2 : 4.7uF/16V(0805)

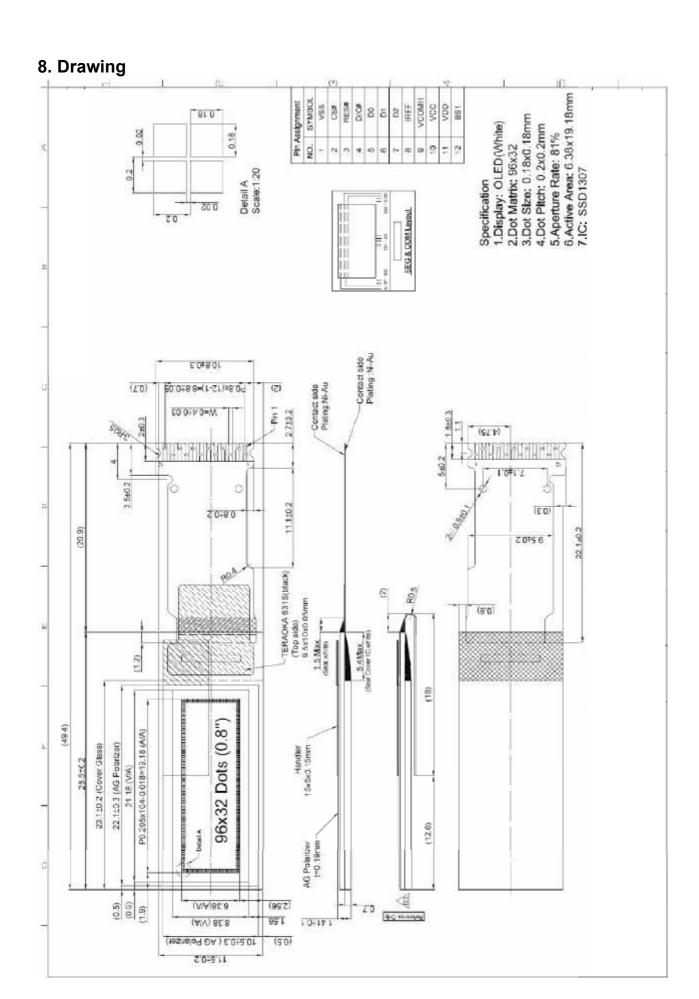
C3: 0.1uF/16V(0603)

R1: 2M ohm 1%(0603)

R2 · R3 : 10K ohm (0603)

This circuit is for I²C Interface

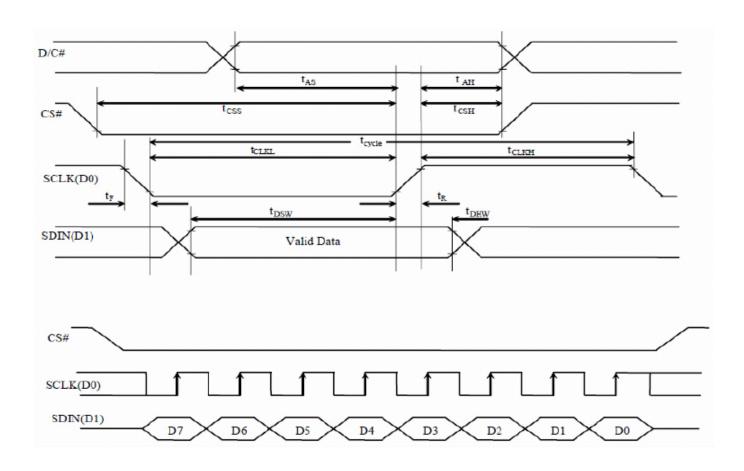
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9. SSD1307controller data

9.1 Timing Characteristics SPI Interface

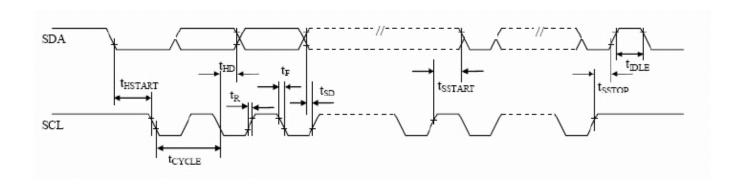
Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	100	-	-	ns
t _{AS}	Address Setup Time	15	-	-	ns
t _{AH}	Address Hold Time	15	-	-	ns
t _{CSS}	Chip Select Setup Time	20	-	-	ns
t _{CSH}	Chip Select Hold Time	10	-	-	ns
t _{DSW}	Write Data Setup Time	15	-	-	ns
t _{DHW}	Write Data Hold Time	15	-	-	ns
t _{CLKL}	Clock Low Time	20	-	-	ns
t _{CLKH}	Clock High Time	20	-	-	ns
t _R	Rise Time	-	-	40	ns
t _F	Fall Time	-	-	40	ns



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I2C Interface

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	2.5	-	-	us
tHSTART	Start condition Hold Time	0.6	-	-	us
t _{HD}	Data Hold Time (for "SDA _{OUT} " pin)	0	-	-	ns
	Data Hold Time (for "SDA _{IN} " pin)	300	-	-	ns
t _{SD}	Data Setup Time	100	-	-	ns
t _{SSTART}	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
tsstop	Stop condition Setup Time	0.6	-	-	us
t _R	Rise Time for data and clock pin	-	-	300	ns
t _F	Fall Time for data and clock pin	-	-	300	ns
t _{IDLE}	Idle Time before a new transmission can start	1.3	-	-	us



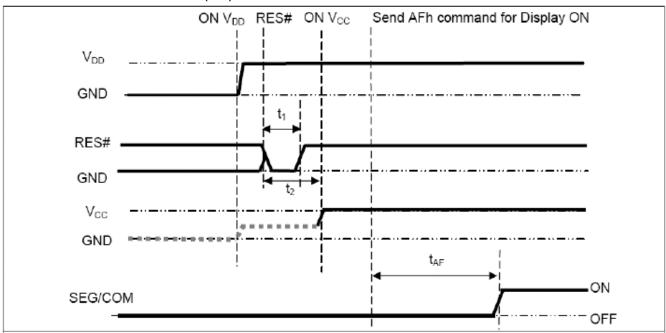
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9.2 Power ON and OFF sequence Application Circuit

9.2.1 POWER ON / OFF SEQUENCE

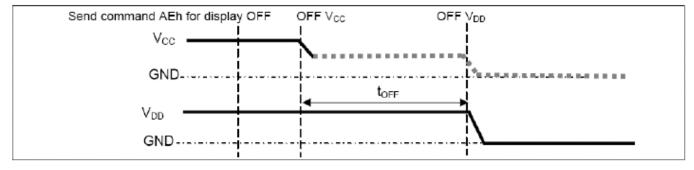
Power ON sequence:

- 1. Power ON VDD.
- 2. After VDD become stable, set RES# pin LOW (logic low) for at least 3us(t1) and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 3us(t2). Then Power ON VCC.(1)
- 4. After Vcc become stable, send command AFh for display ON. SEG/COM will be ON after 100ms(tar).



Power OFF sequence:

- 1. Send command AEh for display OFF.
- 2. Wait until panel discharges completely.
- 3. Power OFF Vcc. (1), (2)
- 4. Wait for toff. Power OFF VDD. (where Minimum toff=80ms, Typical toff=100ms)



Note:

- (1) Since an ESD protection circuit is connected between VDD and VCC, VCC becomes lower than VDD whenever VDD is ON and VCC is OFF as shown in the dotted line of VCC in above figures.
- (2)VCC should be disabled when it is OFF.

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9.3 GRAPHIC DISPLAY DATA RAM ADDRESS MAP

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed.

The size of the RAM is 128 x 39 bits and the RAM is divided into five pages, from PAGE0 to PAGE4, which are used for monochrome 128x39 dot matrix display, as shown in below figures.

When one data byte is written into GDDRAM, all the rows image data of the same page of the current column are filled (i.e. the whole column (8 bits) pointed by the column address pointer is filled.). Data bit D0 is written into the top row, while data bit D7 is written into bottom row. For PAGE4, bit D7 is treated as don't care bit.

For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software. For vertical shifting of the display, an internal register storing the display start line can be set to control the portion of the RAM data to be mapped to the display (command D3h).

GDDRAM pages structure of SSD1307												
Segment re- mapping (command A1h)	SEG127	SEG126	SEG125	SEG124		SEG4	SEG3	SEG2	SEG1	SEGO		
Segment re- mapping (command A0h [RESET])	SEG0	SEG1	SEG2	SEGS		SEG123	SEG124	SEG125	SEG126	SEG127		
Page Data	ODC0	∞L1	2100	ണ		COL123	00L124	00L125	∞L126	∞L127	COM Output Scan Direction (command C0h [RESET])	COM Output Scan Direction (command C8h)
D0	Ŭ	Ŭ	Ŭ)))	Ú)	COM0	COM38
D1			2								COM1	COM37
D2		1	A 3				D- 6			1	COM2	COM36
0 D3											COM3	COM35
D4	4			\vdash				\vdash	$oxed{\Box}$		COM4	COM34
D5	_					g 01				c 5	COM5	COM33
D6	_						0	\vdash	\vdash		COM6	COM32
D7	_										COM7	COM31
D0	-	_				_					COM8	COM30
D1	+-										COM9	COM29
D2	-		4			2 15					COM10	COM28
1 D3	+							\vdash	\vdash		COM11	COM27
D4	+							\vdash			COM12	COM26
D5	+-	-				_		_	_	_	COM13 COM14	COM25
D6 D7	+			*					\vdash	-	COM15	COM24 COM23
D0	+					6 9	6 9	_	\vdash		COM16	COM22
D1	+				Fach have some				L :4		COM17	COM21
D2	+				Each box repre	esen	is c	ne	DIL		COM17 COM18	COM21
D0	+		4 4		of image data					-	COM19	COM19
2 D3	+					-	9 - 0				COM20	COM18
D5	+	81 - 87	35 Y		***************************************	3 8	12 17	\vdash		11 10	COM21	COM17
D6	+		2 0			2 33		\vdash			COM22	COM16
D7	+					2 70		\vdash		-	COM23	COM15
D0	+	_				\vdash		\vdash	Н		COM24	COM14
D1	+									- 12	COM25	COM13
D2	+										COM26	COM12
D3	+	1 0	2 6			0 00	iii.				COM27	COM11
3 D3	+	1				3 -	S	\vdash	Н		COM28	COM10
D5	+	T									COM29	COM9
D6	1										COM30	COM8
D7											COM31	COM7
D0	1	9	A 7			V 0	e e			171	COM32	COM6
D1	1						10 N				COM33	COM5
D2											COM34	COM4
4 D3			00 0			3	· .				COM35	COM3
D4	1	П			Address state						COM36	COM2
D5		· 10	X - X			× 65	ei n			-	COM37	COM1
D6							1		П		COM38	COM0
D7	_	_	_	_	Don't care bit	_	_	_		_		

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10. Quality Assurance

10.1 Inspection conditions

1. The inspection and meaurement are performed under the following conditions,

2. unless otherwise specified.

3. Temperature: 25±5°C4. Humidity: 50±10%R.H.

5. Distance between the panel and eyes of the inspector≥30cm

10.2 Inspection Parameters

Severity	Inspection Item	ection Item Defect		
		(1) Non-displaying		
	1. Panel	(2) Line defects		
	i. Failei	(3) Malfunction		
Major		(4) Glass cracked		
Defect	2. Film	(1) Film dimension out of	Can not be	
	2.1 11111	specification	assembled	
	3. Dimension	(1) Outline dimension out		
	O. Diricholori	of specification		
		(1) Glass scratch		
	1. Panel	(2) Glass cutting NG		
		(3) Glass chip		
		(1) Polarizer scratch	Appearance	
Minor	2. Polarizer	2. Polarizer (2) Stains on surface		
Defect		(3) Polarizer bubbles	defect	
	2 Dioplaying	(1) Dim spot 、	uelect	
	3. Displaying	Bright spot \ dust		
	4. Film	(1) Damage		
	7.1 11111	(2) Foreign material		

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Description	Criterion					
	Width (mm) W	Length (mm) L	number of pieces permitted			
1. Glass scratch	W≦0.03 0.03< W≦0.05 0.05< W	Ignore L≦3	Igno 3 Non		Minor	
	beyond A.A.		Igno			
2. Polarizer bubble	Size $ \Phi \leq 0.2 $ $ 0.2 < \Phi \leq 0.5 $ $ 0.5 < \Phi $ beyond A A	number pieces per Ignor 2 0	mitted re		Minor	
	beyond A.A.	Ignor	е			
	average	numbe	r of			
3. Dimming spot \ Lighting spot \ Dust	$\begin{array}{c} D \leq 0.1 \\ 0.1 < D \leq 0.15 \\ 0.15 < D \leq 0.2 \\ 0.2 < D \\ \text{beyond A.A.} \\ D = (\text{long diameter}) \\ \text{Pixel off is not allowed} \end{array}$	1 0 Ignor er + short diam	re		Minor	

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10.3 WARRANTY POLICY

WE Will provide one-year warranty for the products only if under specification operating conditions.

If there are functional defects found during the period of warranty, the defective products would be replaced on a one-to-one basis.

We would not be responsible for any direct/indirect liabilities consequential to any parties.

10.4 MTBF

10.4.1 .MTBF based on specific test condition is 25K hours.

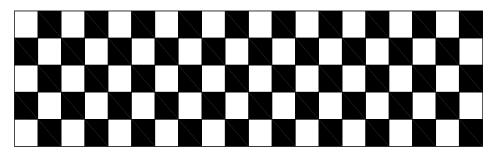
10.4.2 Test Condition:

10.4.2.1 Supply Voltage: Vcc=12V

10.4.2.2 Luminance: 120cd/m2

10.4.2.3 Operation temperature and humidity: 25 °C and 50%RH

10.4.2.4 Run-Patterns:



10.4.3 Test Criteria:

Luminace has decayed to less than 50% of the initial measured luminance.

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11.Reliability

■Content of Reliability Test

NO.	Items.	Specification	Applicable Standard
1	High temp. (Non-operation)	85°C, 240hrs	
2	High temp. (Operation)	70°C, 120hrs	
3	Low temp. (Operation)	-40°C, 120hrs	
4	High temp. / High. humidity (Operation)	65°C, 90%RH, 120hrs	
5	Thermal shock(Non-operation)	-40°C ~85°C (-40°C /30min; transit /3min; 85°C /30min; transit /3min) 1cycle: 66min, 100 cycles.	
6	Vibration	Frequency : 5~50HZ, 0.5G Scan rate : 1 oct/min Time : 2 hrs/axis Test axis : X, Y, Z	

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for item 1 & 4 & 5.

Criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: >50% of initial value.
- 4. Current consumption: within ±50% of initial value.

Reliability Test

Only guarantees the reliability of the panel under the test conditions and durations listed in the specification, and is not responsible for any test results that are conducted using more stringent conditions and/or with lengthened durations. Also, when the testing the panel in a chamber or oven, make sure they won't produce any condensation on the panel, especially on the electrical leads, before lighting on the panel to see if it passes the test. Also the panel should rest for about an hour at room temperature and pressure before the measurement, as indicated in the specification. Be aware that one should use fresh panel for each of the reliability test items listed in the specification, in other words, don't use the panels that were tested for subsequent tests.

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